

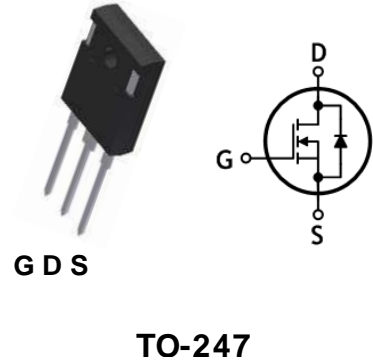
SWITCHING REGULATOR APPLICATION

Features

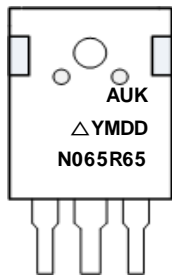
- 650V Super-junction MOSFET
- Low FOM $R_{DS(on)} * Q_g$
- Low drain-source On-resistance: $R_{DS(on)}=0.065\Omega$ (Max.)
- 100% avalanche tested
- RoHS compliant device

Ordering Information

Part Number	Marking	Package
SJMN065R65W	N065R65	TO-247



Marking Information



- Column 1: Manufacturer
Column 2: Production Information
e.g.) Δ YMDD
-. Δ : Factory Management Code
-. YMDD: Date Code (Year, Month, Daily)
Column 3: Device Code

Absolute maximum ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit	
Drain-source voltage	V_{DSS}	650	V	
Gate-source voltage	V_{GSS}	± 30	V	
Drain current (DC) (Note 1)	I_D	$T_c=25^\circ\text{C}$	51	A
		$T_c=100^\circ\text{C}$	32	A
Drain current (Pulsed) (Note 1)	I_{DM}	204	A	
Single pulsed avalanche energy (Note 2)	E_{AS}	650	mJ	
Repetitive avalanche current (Note 1)	I_{AR}	10	A	
Repetitive avalanche energy (Note 1)	E_{AR}	43.1	mJ	
Power dissipation	P_D	431	W	
Diode dv/ dt ruggedness (Note 3)	dv/ dt	15	V/ ns	
MOSFET dv/ dt ruggedness (Note 4)	dv/ dt	50	V/ ns	
Junction temperature	T_J	150	$^\circ\text{C}$	
Storage temperature range	T_{stg}	-55~150	$^\circ\text{C}$	

Thermal Characteristics

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to case	$R_{th(j-c)}$	Max. 0.29	°C/W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 50	

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu\text{A}$, $V_{DS}=V_{GS}$	2	-	4	V
Drain-source cut-off current	I_{DSS}	$V_{DS}=650\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=\pm 30\text{V}$	-	-	± 100	nA
Gate leakage current	$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=19.4\text{A}$	-	0.055	0.065	Ω
Drain-source on-resistance	R_g	$f=1\text{MHz}$, Open drain	-	0.5	-	Ω
Internal gate resistance	C_{ISS}	$V_{DS}=100\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	4510	-	pF
Input capacitance	C_{OSS}		-	120	-	
Output capacitance	C_{RSS}		-	5.4	-	
Reverse transfer capacitance	$t_{d(on)}$	$V_{DD}=300\text{V}$, $I_D=19.4\text{A}$, $R_G=10\Omega$, $V_{GS}=10\text{V}$	-	85	-	ns
Turn-on delay time (Note 5)	t_r		-	55	-	
Rise time (Note 5)	$t_{d(off)}$		-	210	-	
Turn-off delay time (Note 5)	t_f		-	15	-	
Fall time (Note 5)	Q_g		-	94	-	
Total gate charge (Note 6)	Q_{GS}	$V_{DS}=400\text{V}$, $V_{GS}=10\text{V}$, $I_D=38.8\text{A}$	-	22	-	
Gate-source charge (Note 6)	Q_{gd}		-	30	-	

Source-Drain Diode Ratings and Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	I_S	Integral reverse diode in the MOSFET	-	-	51	A
Source current (Pulsed)	I_{SM}		-	-	204	A
Forward voltage	V_{SD}	$V_{GS}=0\text{V}$, $I_S=51\text{A}$	-	-	1.7	V
Reverse recovery time (Note 5, 6)	t_{rr}	$I_S=19.4\text{A}$, $V_{GS}=0\text{V}$ $dI_S/dt=50\text{A}/\mu\text{s}$	-	460	-	ns
Reverse recovery charge (Note 5, 6)	Q_{rr}		-	7.4	-	μC

Note:

1. Calculated continuous current based on maximum allowable junction temperature
2. $L=10\text{mH}$, $I_{AS}=10\text{A}$, $V_{DD}=150\text{V}$, Starting $T_J=25^\circ\text{C}$
3. $I_S \leq 9.7\text{A}$, $V_{DS} \leq 400\text{V}$, $dI_S/dt \leq 100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$
4. $V_{DS} \leq 400\text{V}$, $I_S \leq 9.7\text{A}$
5. Guaranteed by design, not subject to production testing
6. Pulse test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

Typical Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

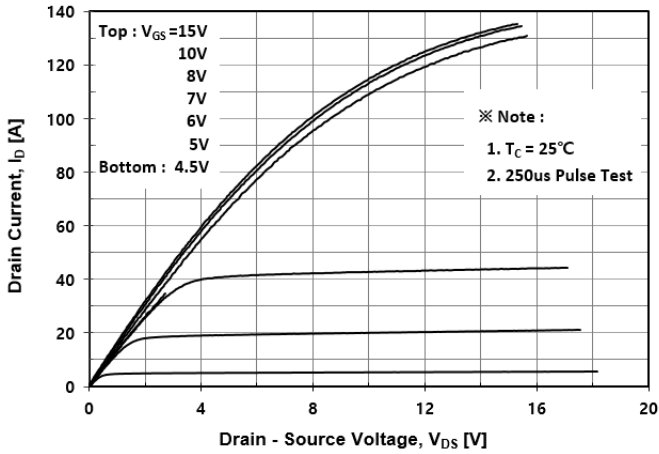


Fig. 2 Typical Transfer Characteristics

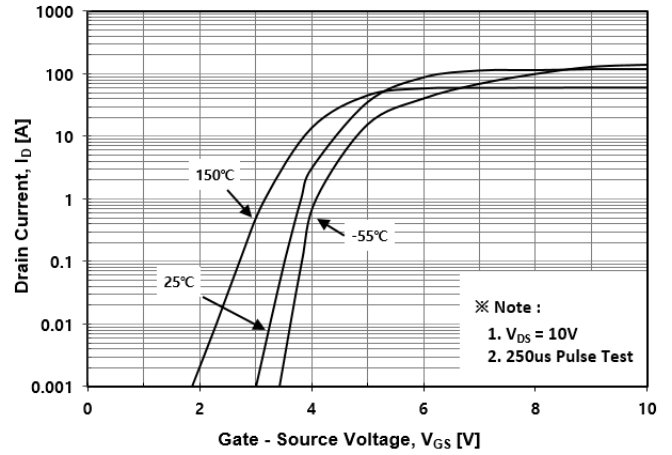


Fig.3 On-Resistance Variation with Drain Current and Gate Voltage

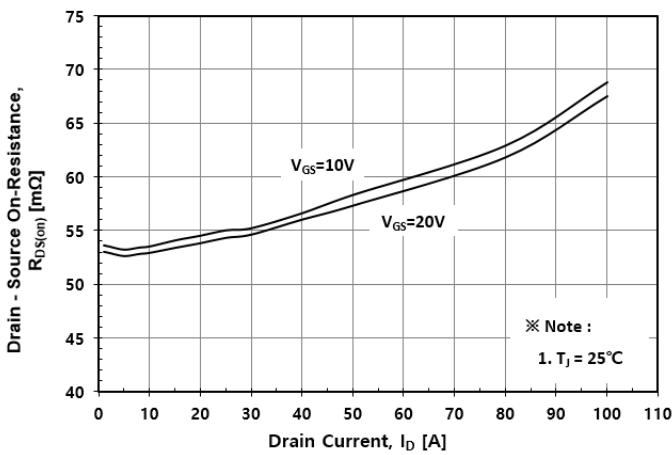


Fig. 4 Body Diode Forward Voltage Variation with Source Current

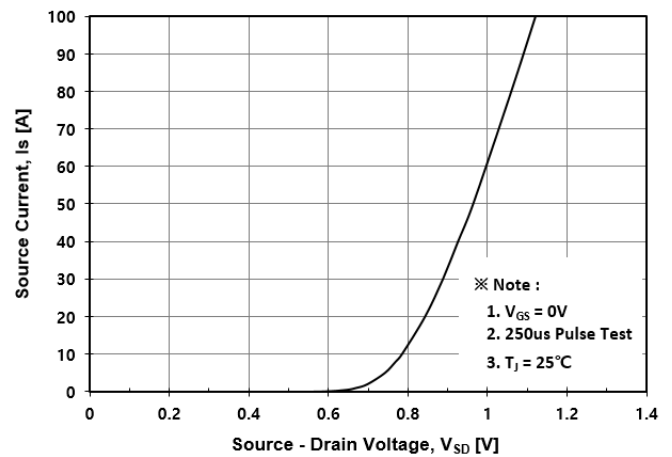


Fig. 5 Typical Capacitance Characteristics

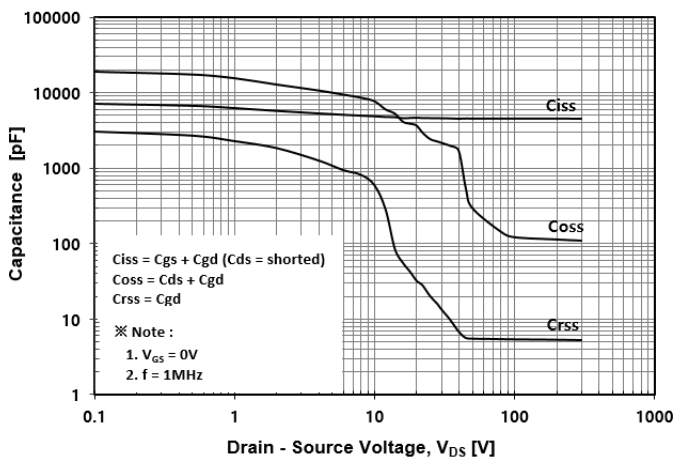


Fig. 6 Typical Total Gate Charge Characteristics

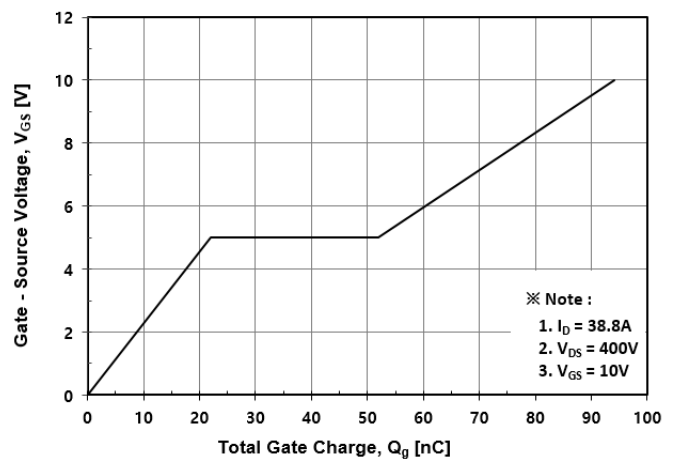


Fig. 7 Breakdown Voltage Variation vs. Temperature

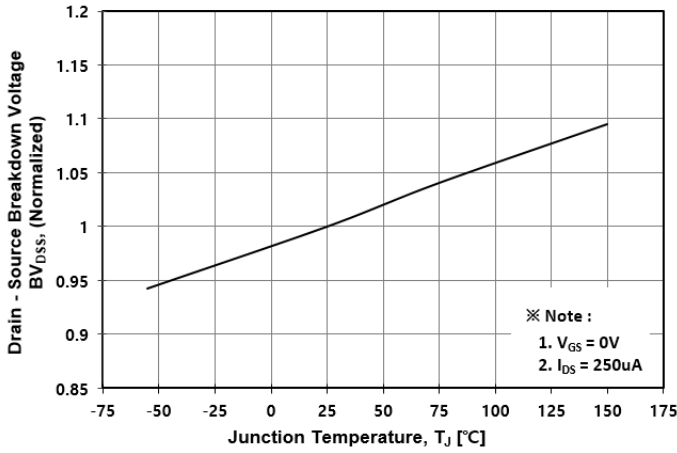


Fig. 8 On-Resistance Variation vs. Temperature

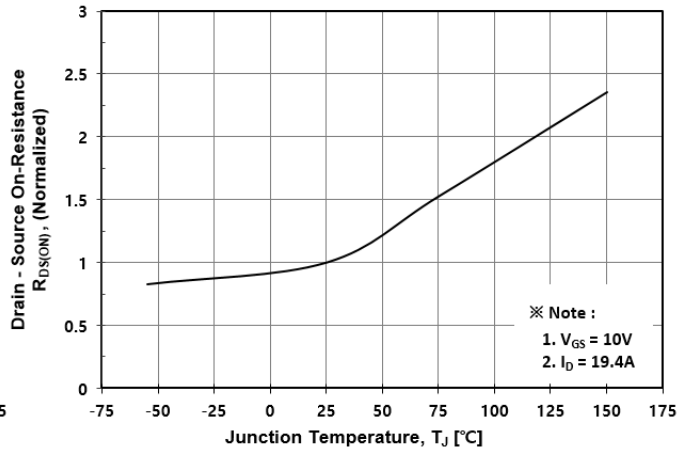


Fig. 9 Maximum Drain Current vs. Case Temperature

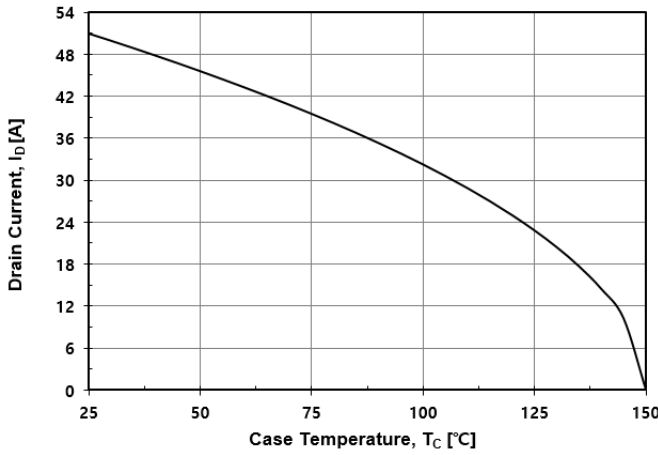


Fig. 10 Maximum Safe Operating Area

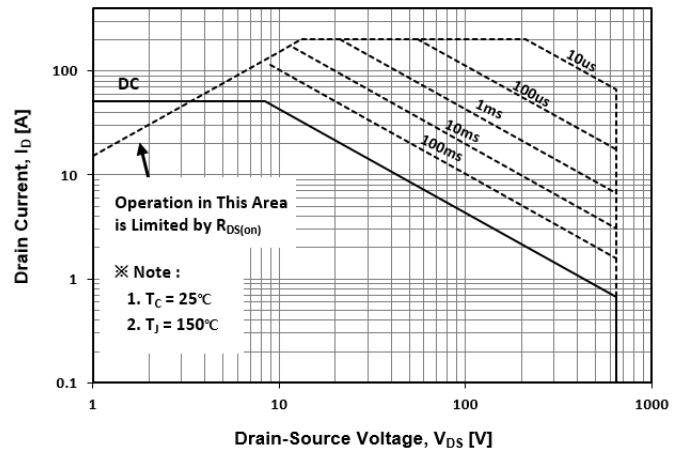


Fig. 11 Transient Thermal Impedance

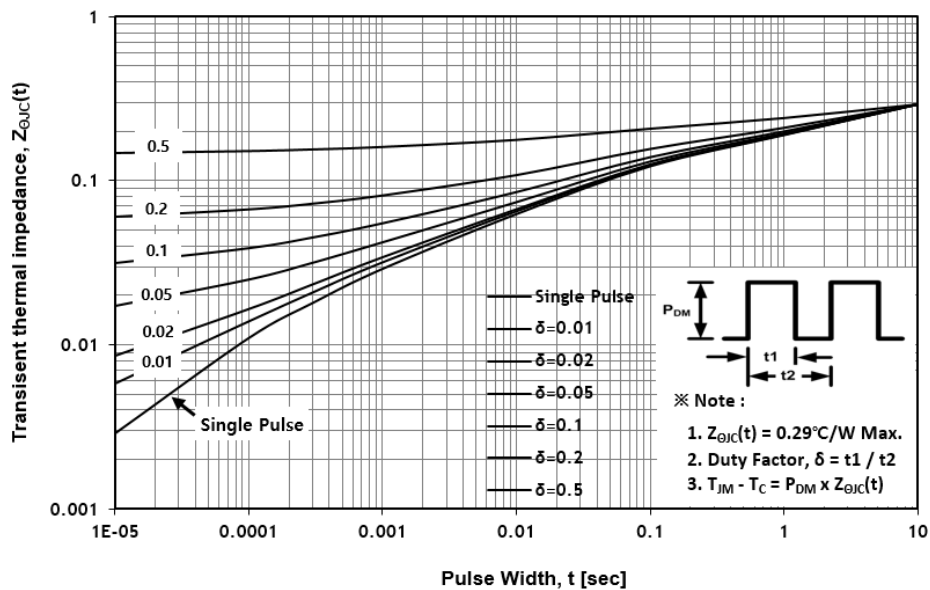


Fig. 12 Gate Charge Test Circuit & Waveform

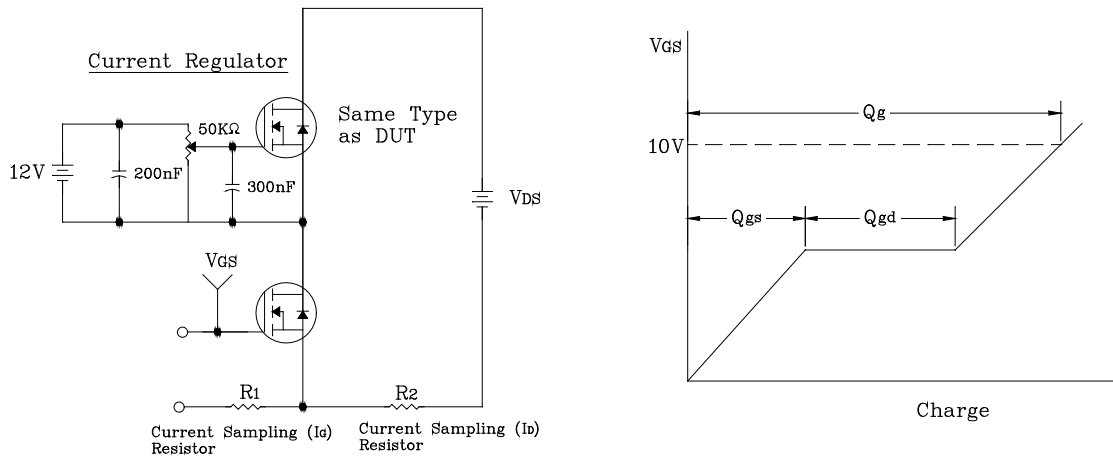


Fig. 13 Resistive Switching Test Circuit & Waveform

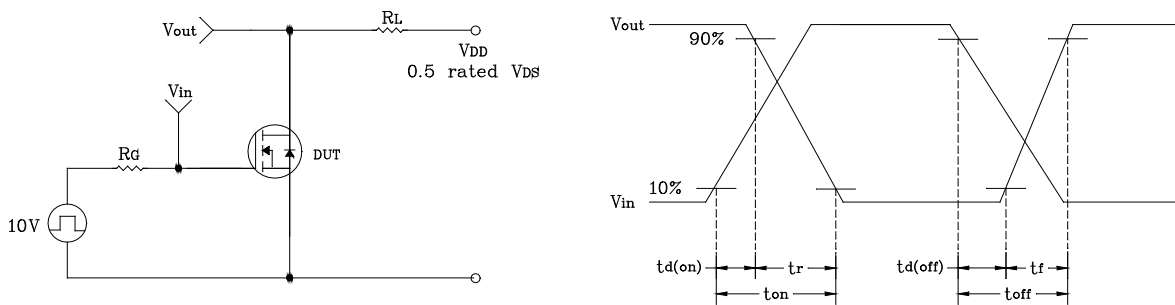


Fig. 14 E_{AS} Test Circuit & Waveform

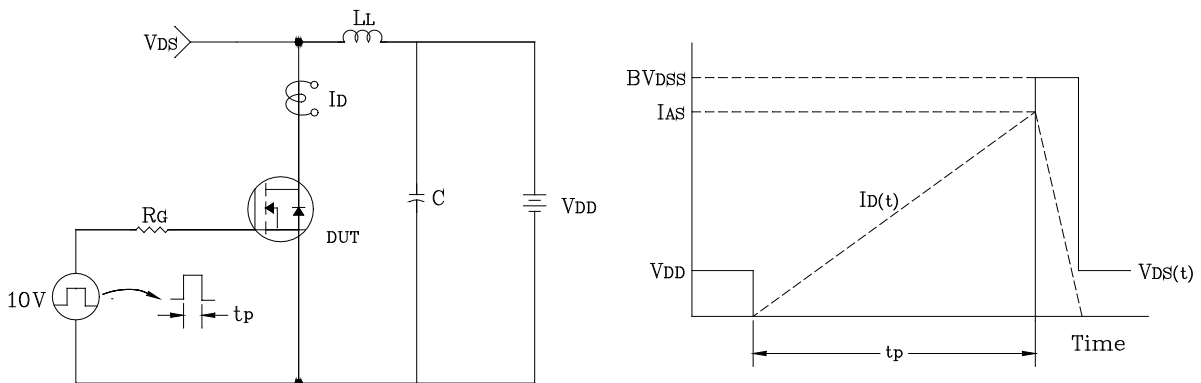
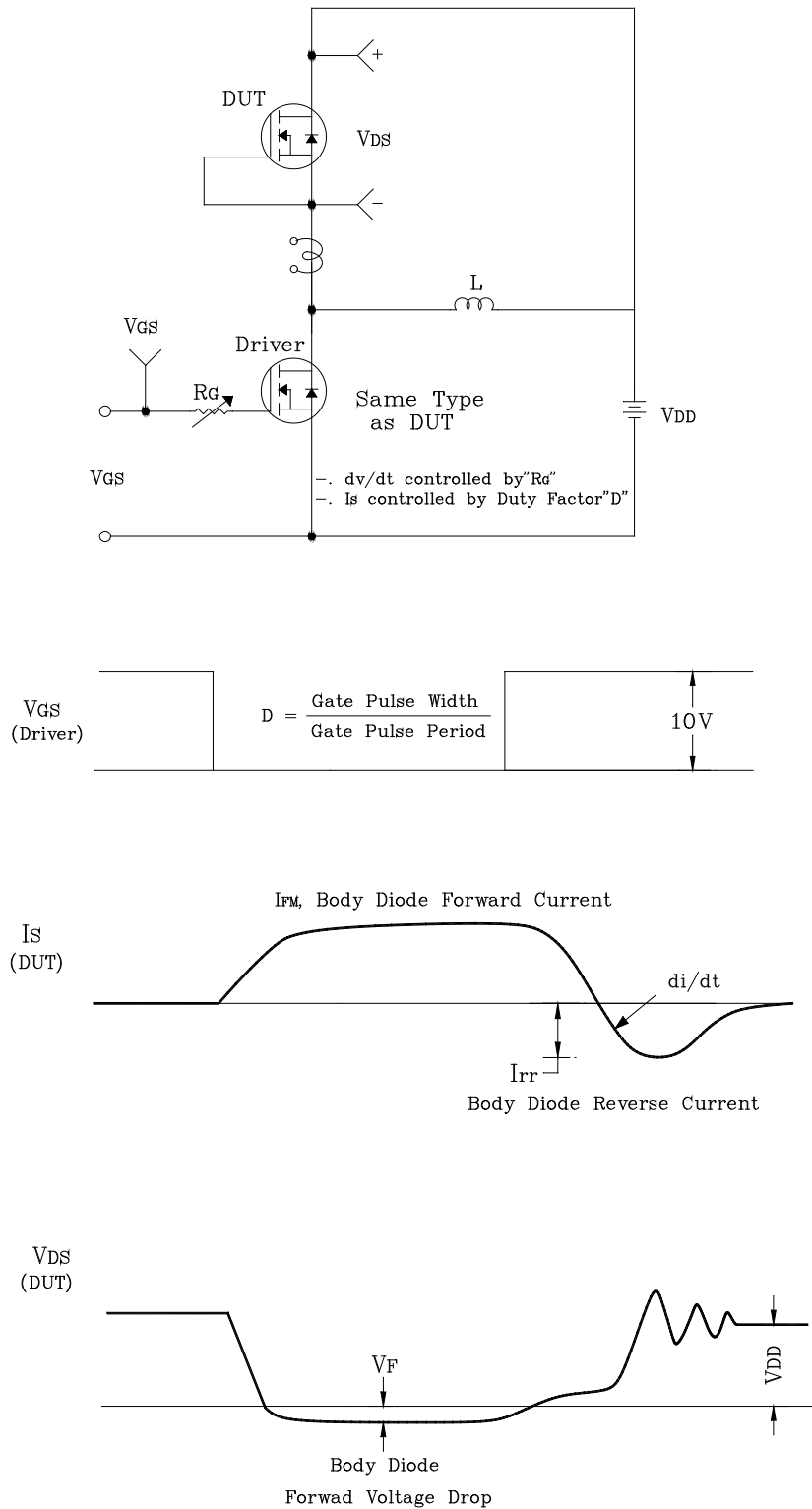
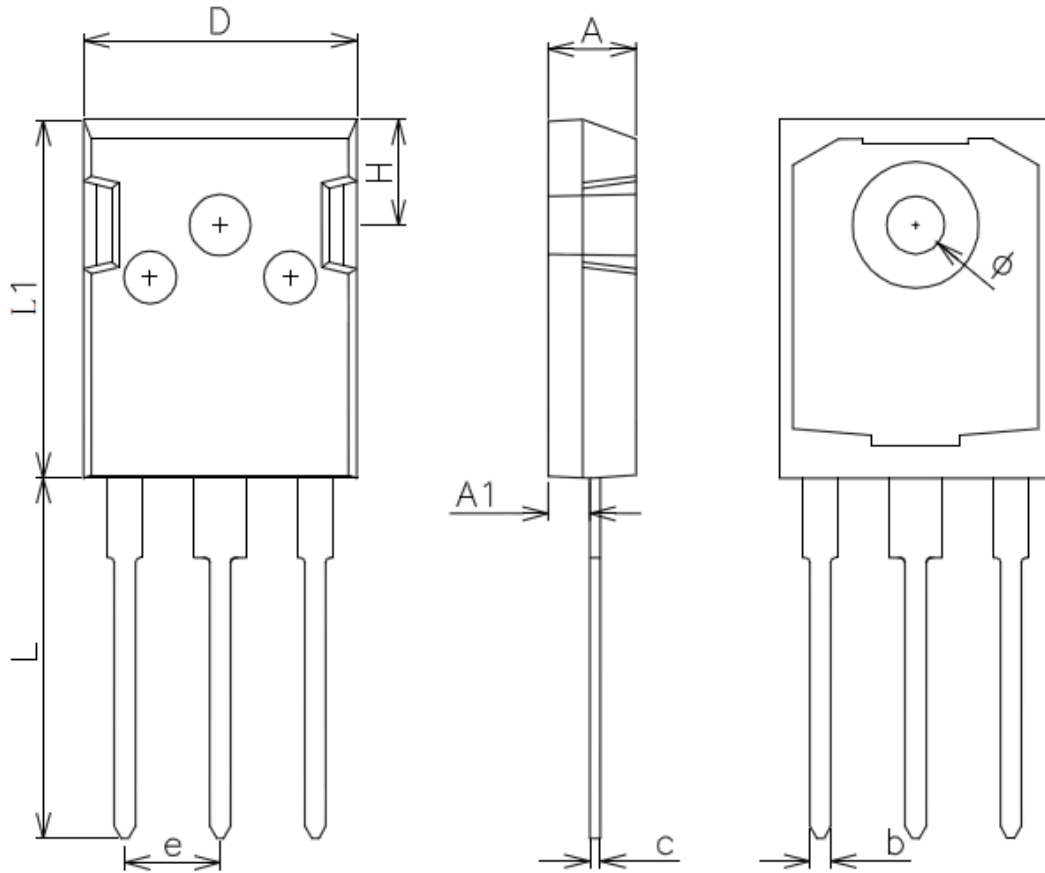


Fig. 15 Diode Reverse Recovery Time Test Circuit & Waveform



Package Outline Dimensions (Unit: mm)



SYMBOL	MILLIMETERS		
	MIN	Nominal	MAX
A	4.80	5.00	5.20
A1	2.41 REF		
b	1.00	1.20	1.40
c	0.40	0.60	0.80
D	15.60	15.80	16.00
e	5.45 REF		
H	6.15 REF		
L	19.35	19.95	20.55
L1	20.80	21.00	21.20
ϕ	3.20	3.50	3.80

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